

ABSTRACT OF THE DISCLOSURE

A dual chips stacked packaging structure. A first chip comprises an active surface and an opposing non-active surface, the active surface consisting of a central area and a peripheral area having a plurality of first bonding pads. A lead frame comprises a plurality of leads and a chip paddle having a first adhering surface and a second adhering surface, with the first adhering surface adhering to the active surface of the first chip in such a way as to avoid contact with the first bonding pads. A second chip comprises an active surface and an opposing non-active surface connecting with the second adhering surface of the chip paddle, and the active surface consisting of a central area and a peripheral area having a plurality of second bonding pads. Parts of the wires electrically connect with the first bonding pad and the leads, and parts of the wires electrically connect with the second bonding pad and the leads.